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1999
Start of the electronic SI project (ASET)
~ Packaging ~

As the business condition became more difficult towards the end of 1990s, burden of each company on package development costs became severe. The domestic semiconductor companies started a national project focusing on packaging technology leading into the 21st century and proceeded with development. The project was set as "Three-dimensional Mounting Process" development project with the focus on TSV (Through Silicon Via) technology. The development period was 5 years from 1999 to 2003, and trial manufacturing CCD camera module and so on was done.
Development promotion unit was Electronic SI (Silicon Integration) group of ASET (Ultra Advanced Semiconductor Research Association).

The left figure describes the multilayer structure by TSV, the center is a photograph of the prototype, and the right is an example of application to CCD camera module.

The TSV technology of this project was a package technology that challenged the limits of the miniaturization by Moore's Law, searching for a way to large capacity memory by multilayering of DRAM elements.

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